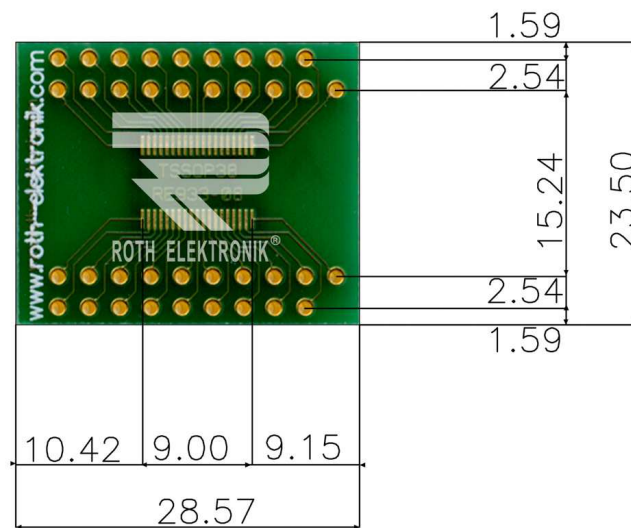


RE933-08

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSSOP 38
- Pitch: 0.50 mm (173 mil)
- Hole diameter 1.00 mm
- Size 23.50 x 28.57 mm

Module-No. Pitch mil Pin Size (mm)

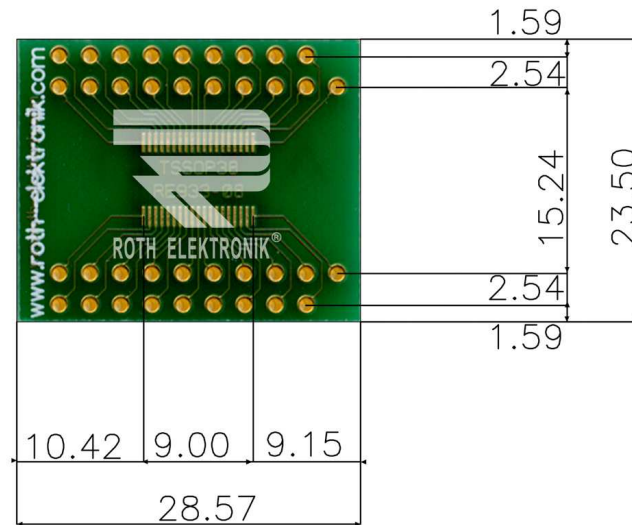
RE933-08 0.500 mm 19.6 38 6.100 (240 mil)



RE933-08

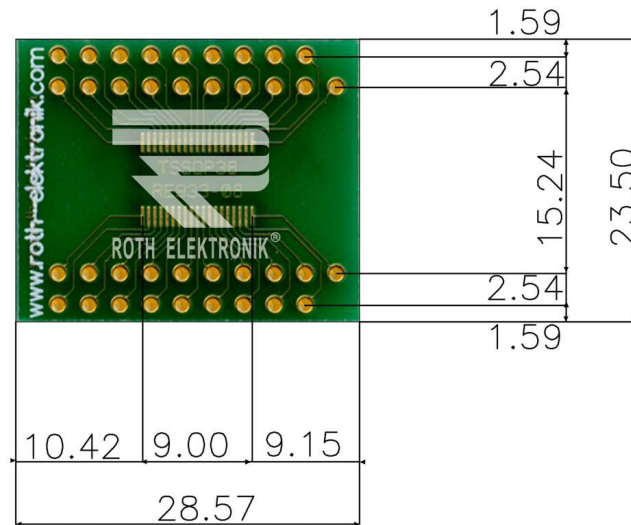
- Epoxydglashartgewebe FR4 1,50 mm
 - Zweiseitig 35 µm Cu
 - Durchkontaktiert (PTH)
 - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
 - Adaptionsplatine für TSSOP 38
 - Pitch: 0,50 mm (173 mil)
 - Lochdurchmesser 1,00 mm
 - Größe 23,50 x 28,57 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE933-08 0,500 mm 19,6 38 6,100 (240 mil)



RE933-08

- Fibre de verre époxyde FR4 1,50 mm
 - Double face 35 µm Cu
 - Métallisation des trous (PTH)
 - Surface avec Ni/Au chimique et un laque d'arrêt de soudure
 - Platine d'adaptation pour TSSOP 38
 - Pitch: 0,50 mm (173 mil)
 - Perforation 1,00 mm Ø
 - Dimensions 23,50 x 28,57 mm
- Module-No. Pitch mil Pin Dimensions (mm)
RE933-08 0.500 mm 19.6 38 6.100 (240 mil)



RE933-08

- Fibra de vidrio epoxídica FR4 1,50 mm
 - Por dos lados 35 µm de Cu
 - Agujeros con contactos metalizados (PTH)
 - Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
 - Adaptador para TSSOP 38
 - Pitch: 0,50 mm (173 mil)
 - Diámetro de agujeros 1,00 mm
 - Tamaño 23,50 x 28,57 mm
- Módulo-No. Pitch mil Pin Tamaño (mm)

RE933-08 0.500 mm 19.6 38 6.100 (240 mil)